

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) A method for manufacturing a relief material for seamless printing using a liquid-state photosensitive resin, the method comprising:

setting a workpiece using either of a printing cylinder or a printing sleeve, which is integrally supported by a metallic mandrel, to a holding and rotating device for holding and rotating the workpiece;

supplying a liquid-state photosensitive resin having a viscosity that retains an applied shape without being influenced by gravity or centrifugal force due to rotation, to a resin receiving plate which has an angle of inclination and whose front end has a doctor blade shape from a resin supplying device in a linear mode by linearly moving the resin supplying device in an axial direction of the workpiece, at least one end of the resin receiving plate in the axial direction having a resin flow preventive movable dam that is linearly movable in the axial direction of the workpiece;

applying the liquid-state photosensitive resin supplied to the resin receiving plate to an outer periphery of the workpiece at an applied thickness with the front-end of the resin receiving plate while rotating the workpiece; and

exposing high-intensity ultraviolet light to the liquid-state photosensitive resin applied to the outer periphery of the workpiece while rotating the workpiece to form a photosensitive resin cured layer by optically curing the liquid-state photosensitive resin so that it can be carved by an infrared laser beam.

2. (Cancelled).

3. (Previously Presented) The method according to claim 1, further comprising shaping the surface of the photosensitive resin cured layer.

4. (Previously Presented) The method according to claim 1, wherein the viscosity of the liquid-state photosensitive resin supplied ranges from 6 to 50kPa ·s at 20°C and the ultraviolet light in the exposing step has a wavelength area of from 200 to 400 nm and an ultraviolet intensity of 10mW/ cm² or more.

5. (Previously Presented) The method according to claim 1, wherein in the supplying step, the liquid-state photosensitive resin is supplied to the resin receiving plate from at least one or more resin supplying nozzles of the resin supplying device.

6. (Currently Amended) The method according to claim 1, wherein the liquid-state photosensitive resin is applied to the outer periphery of the workpiece at a desired thickness while gradually expanding a gap between the front-end of the resin receiving plate and the outer periphery of the workpiece by moving the resin receiving plate vertically relative to the axis of the workpiece in the applying step.

7. (Previously Presented) The method according to claim 1, wherein the supplying step is performed a plurality of times.

8. (Previously Presented) The method according to claim 1, further comprising a first removing step for removing extra cured photosensitive resin from the cured layer that exceeds a desired width in the exposing step to a desired thickness in parallel with or after a shaping step.

9. (Previously Presented) The method according to claim 8, further comprising a carving step for fusion-removing cured photosensitive resin from the cured layer by rotating the workpiece while linearly-moving a laser carving device for carving

the photosensitive resin cured layer on the outer periphery of the workpiece in an axial direction of the workpiece and focusing one or more infrared laser beams applied from the laser carving device on the photosensitive resin cured layer in accordance with the control of a digital image recording signal after either of the shaping step or the first removing step.

10. (Previously Presented) The method according to claim 9, further comprising a second removing step for removing cured photosensitive resin from the cured layer in an area in which formation of a relief image in the carving step is unnecessary to a desired thickness in parallel with or after the shaping step.

11. (Previously Presented) The method according to claim 10, wherein in the second removing step, only a relief image forming area is laser carved by performing interlaced scanning for moving the laser carving device at a high speed in an image unnecessary area in the carving step when the photosensitive resin cured layer in the area in which formation of the relief image is unnecessary is removed to a desired thickness.

12. (Previously Presented) The method according to claim 9, further comprising a cleaning step for cleaning the photosensitive resin cured layer with a cleaning device for spraying cleaning fluid having a pressure of from 0.2 to 30 MPa and a temperature of from 40 to 140°C onto the cured layer after any one of the carving step, removing step, and shaping step.

13. (Previously Presented) The method according to claim 9, further comprising a post-exposing step for applying ultraviolet light to a relief image layer on

the outer periphery of the workpiece while rotating the workpiece after either of the carving step or cleaning step.

14. (Previously Presented) The method according to claim 13, further comprising a surface modifying step for applying a surface modifying agent to the relief image layer for modifying the surface of the relief image layer of the workpiece while rotating the workpiece and then drying the agent.

15. (Previously Presented) The method according to claim 14, wherein in the surface modifying step forcible heating and drying is performed while applying the surface modifying agent to the relief image layer.

16-26. (Cancelled).

27. (Previously Presented) The method according to claim 1, wherein the angle of inclination is an angle of from 15 to 75°.

28. (Currently Amended) The method according ~~[[o]]to~~ claim 1, wherein the applied thickness ranges from 0.5 to 3 mm.

29. (Previously Presented) The method according to claim 1, wherein the resin supplying device includes a resin supplying nozzle.

30. (Previously Presented) The method according to claim 29, wherein the linear mode is a mode in which the resin supplying nozzle supplies the liquid-state photosensitive resin to the resin receiving plate while the resin supplying nozzle linearly moves in an axial direction of the workpiece.

31, (Previously Presented) The method according to claim 1, further comprising a carving step for fusion-removing cured photosensitive resin from the cured layer by rotating the workpiece while linearly-moving a laser carving device for carving

the photosensitive resin cured layer on the outer periphery of the workpiece in an axial direction of the workpiece and focusing one or more infrared laser beams applied from the laser carving device on the photosensitive resin cured layer in accordance with the control of a digital image recording signal after either of a shaping step or a first removing step.